



Title of Change:	MSL3 to MSL1 change for device NCV97311MW50AR2G	
Effective date:	15 February 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or <Kevin.Mathews@onsemi.com>	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>MSL/Packaging/Shipping</u>	
Change Sub-Category(s): <div style="display: flex; flex-wrap: wrap;"> <div style="width: 33%;"><input type="checkbox"/> Manufacturing Site Addition</div> <div style="width: 33%;"><input type="checkbox"/> Material Change</div> <div style="width: 33%;"><input checked="" type="checkbox"/> Datasheet/Product Doc change</div> <div style="width: 33%;"><input type="checkbox"/> Manufacturing Site Transfer</div> <div style="width: 33%;"><input type="checkbox"/> Product specific change</div> <div style="width: 33%;"><input checked="" type="checkbox"/> Shipping/Packaging/Marking</div> <div style="width: 33%;"><input type="checkbox"/> Manufacturing Process Change</div> <div style="width: 33%;"><input type="checkbox"/> Other: _____</div> </div>		
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: None
Description and Purpose: MSL1 qualification completed successfully for NCV97311MW50AR2G. Datasheet will be updated from MSL3 to MSL1 and packaging/shipping will change in accordance with MSL1 requirements. Note: AEC 1-pager attached To view attachments: 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file/s		
List of Affected Parts: NCV97311MW50AR2G		